

Honsu Group 2025Q2 Business Update

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I 、 Company

II 、 Performance

III 、 R&D Investment

IV 、 Product Strategy

V 、 Dividend Policy



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弘塑科技股份有限公司
Grand Process Technology Corporation

Y1993 Founded
Y2011 IPO (3131)
Employee : 230

□ Main Product:

**Wet Process
Equipment (Etch
/PR Strip/ Cleaner) 、
Chemical Deliver
System**



添鴻科技股份有限公司
Chemleader Corporation

Y2013 Merged
Y2002 Founded
Employee : 100

□ Main Product:

**Wet Process
Chemistry
(Etchant、PR
Stripper、
Plating Additive)**



佳霖科技股份有限公司
Challentech International Corporation

Y2019 Merged
Y1987 Founded
Employee : 120

□ Main Product:

**Agent Metrology(X-
Ray、CSAM、EPD) 、
Inspection 、 Wafer
Transfer 、 Robot 、
pump Overhaul**



太引資訊系統股份有限公司
TYNE Systems Corporation

Y2018 Merged
Y2002 Founded
Employee : 30

□ Main Product:

**Software System
Design(EDA、
SPC、FDC、Big
data) Service**

(一)Basic Information

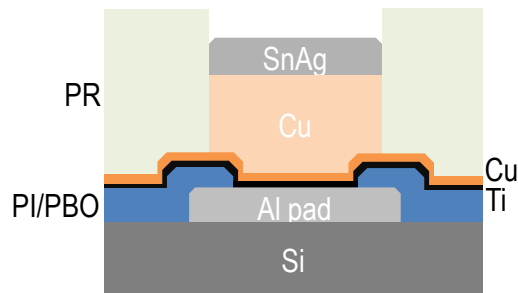
- Founded : 1993/5/7
- Capital : NTD\$ 292,216,000
- Chairman : Robin Chang
- Service Office: HsinChu(HQ) 、 Taichung 、 Tainan 、 Kaohsiung 、 Shanghai

(二)Main Business & Customer

- Business Item :
 - a) Wet Process Equipment(Single Wafer/Wet bench/Combo System)
 - b) Wet Process Chemistry
 - c) Equipment Agent 、 Pump/Robot overhaul
 - d) Big data System Design
- Main Customer :
 - a) TW : tsmc 、 ASE 、 SPIL 、 Micron 、 PTI 、 Amkor 、 Winstek 、 WINsemi 、 EPISIL 、 Mosel 、 TSC 、 TXC 、 Innolux 、 Corning 、 GlobalWafer.....etc.
 - b) CN : TFME 、 QLE 、 Forehope 、 Corning.....etc.



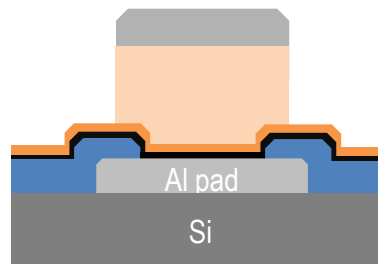
Cu Pillar Plating



- Plating performance
- Reliability

ECD Chemicals
– nt-Cu

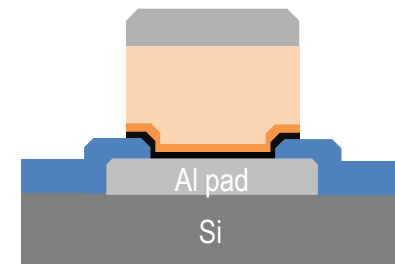
PR Stripping



- Stripper vs. PR and plating recipe
- Stripper vs. PI

Stripper

UBM Etching



- Etching selectivity
- Galvanic effect
- PR residue

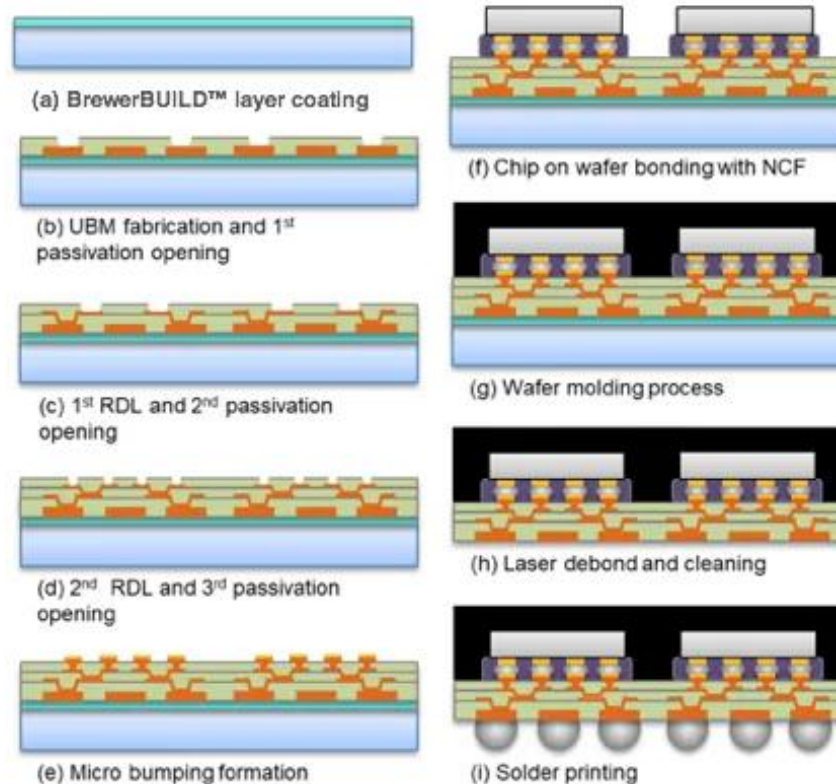
Etchant

Advanced Packaging Wet Solutions

Wafer Clean

PR Strip
UBM Etch

Surface Clean
Via Clean



Gap Clean

Debond Clean
Carrier Clean

Flux Clean
Mask Clean



Wet Bench



Single Wafer Spin



Combo System



Accumulated Installation **>1,000** sets

Accumulated IP : **149**

Avg. Annual R&D Investment : 7%~10%

ASE Y2023 Best Supplier

tsmc Y2022 Best Supplier

tsmc Y2020 Best Supplier

SFIL Y2018 Excellent Vendor

ASE Y2018 Best Supplier

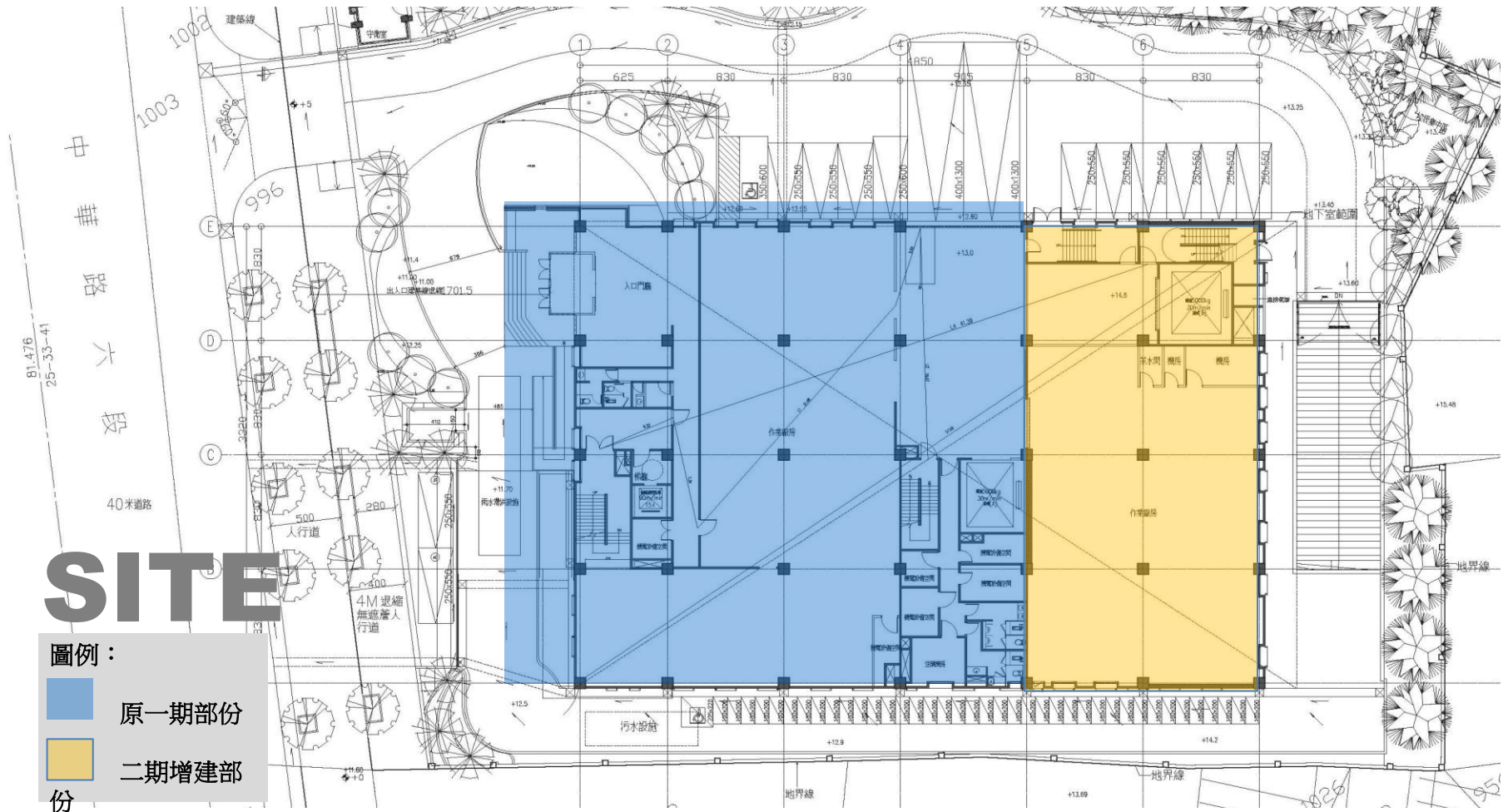
ASE Y2016 Best Supplier



New Factory Plan - GPTC

GPTC Phase2 Factory

- Schedule : Planned 2025/Q3 Ready for production
- Manufacturing footprint : ~ same as Phase1



New Factory Plan - CLC

CLC T-site Factory (total 4 phase, Total Capacity : ~ 2x as H-site)
-Schedule : Phase 1 2024/Aug release production





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Income Statement

MNTD								
Year / account	2020	2021	2022	2023	2,024	2024'1H	2025'1H	YoY
Revenue	2,488	3,658	3,723	3,544	4,073	1,860	2,871	54.4%
Gross Profit	1,126	1,563	1,618	1,488	1,845	806	1,168	45.0%
OP Expense	593	739	859	793	939	431	484	12.4%
OP Net Profit	533	824	759	695	906	375	684	82.4%
Non-OP Revenue	(23)	10	175	54	141	89	(73)	-181.6%
Income before Tax	510	835	934	749	1,047	464	611	31.6%
Net Profit	397	670	722	616	846	377	460	21.9%
EPS(NTD)	13.92	23.47	25.32	21.56	29.07	13	15.79	21.2%
Gross Margin	45.3%	42.7%	43.5%	42.0%	45.3%	43.3%	40.7%	-2.6%
OP Margin	21.4%	22.5%	20.4%	19.6%	22.2%	20.1%	23.8%	3.7%
Margin before Tax	20.5%	22.8%	25.1%	21.1%	25.7%	25.0%	21.3%	-3.7%

Income Statement(By Quarter)

MNTD								
Quarter / account	1Q24	2Q24	3Q24	4Q24	1Q25	2Q25	QoQ	YoY
Revenue	898	962	992	1,222	1,241	1,630	31.4%	69.5%
Gross Profit	388	417	477	562	506	662	30.7%	58.5%
OP Expense	215	216	228	280	230	255	11.0%	17.7%
OP Net Profit	174	201	249	282	277	407	47.0%	102.4%
Non-OP Revenue	45	45	22	45	41	(114)	-377.2%	-355.2%
Income before Tax	218	246	271	327	318	293	-8.0%	19.1%
Net Profit	172	205	217	251	255	205	-19.6%	-0.1%
EPS(NTD)	5.99	7.04	7.42	8.61	8.74	7.05	-19.3%	0.1%
Gross Margin	43.2%	43.4%	48.1%	46.0%	40.8%	40.6%	-0.2%	-2.8%
OP Margin	19.3%	20.9%	25.1%	23.1%	22.3%	25.0%	2.6%	4.1%
Margin before Tax	24.3%	25.5%	27.4%	26.8%	25.6%	18.0%	-7.7%	-7.6%

Revenue Contribution

Revenue Contribution (各子公司營收貢獻比例)

Subsidiaries	Product	2021	2022	2023	2024	2025'1H
GPTC(弘塑)	Equipment	55%	53%	45%	56%	65%
CLC(添鴻)	Chemical	25%	27%	26%	25%	18%
CIC(佳霖)	Distributor	18%	18%	27%	17%	16%
TYNE(太引)	Software	2%	2%	2%	2%	1%



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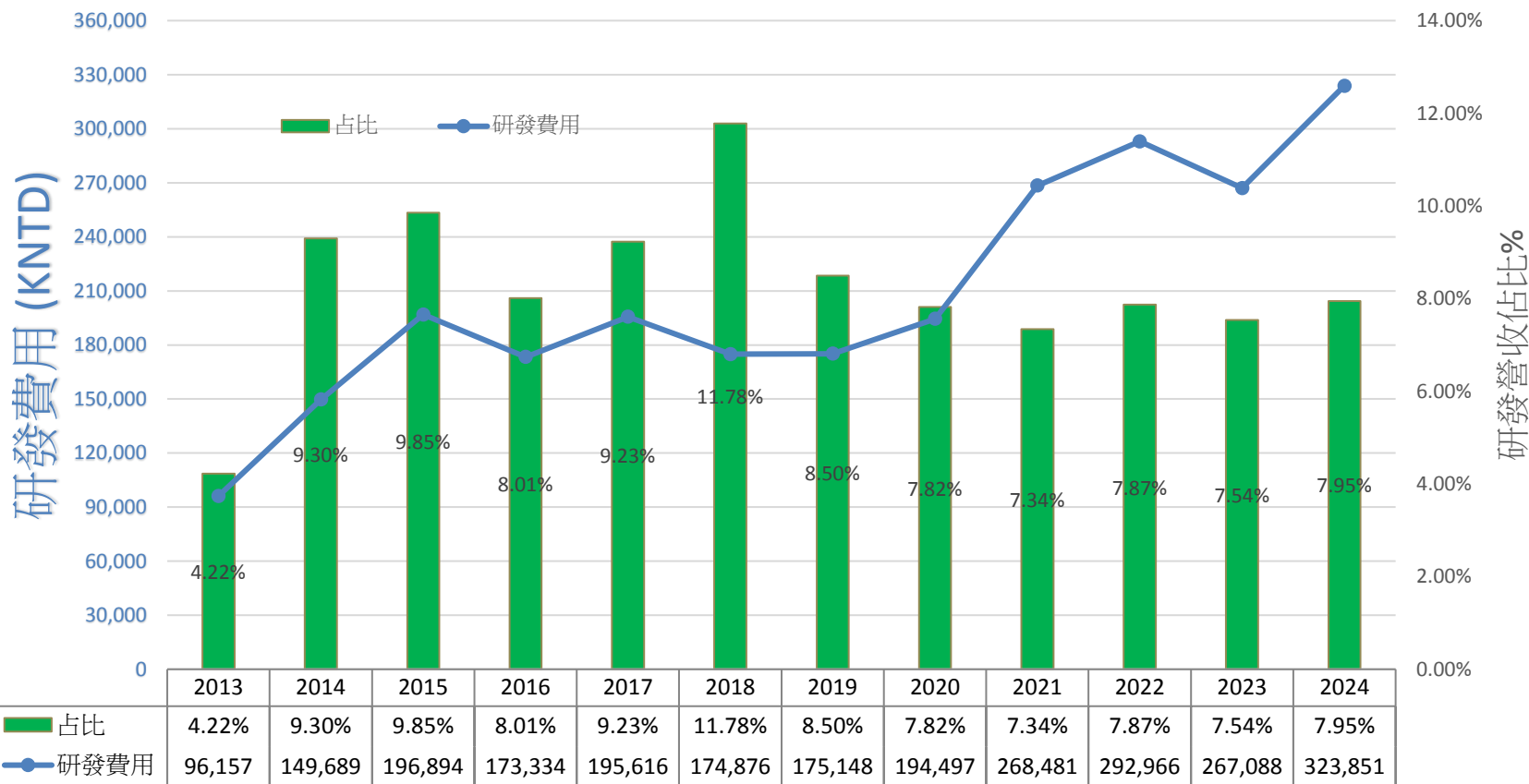
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R&D Expense Investment

弘塑科技研發費用及營收佔比(Group)





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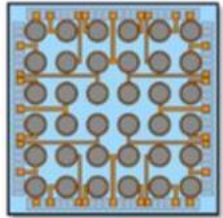
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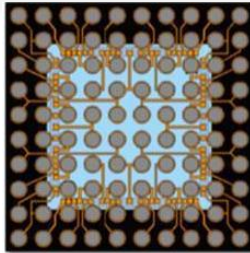
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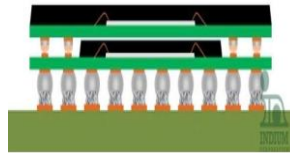
Process Application Opp.



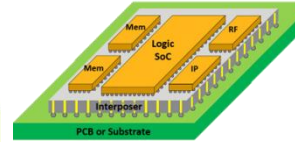
Fan-In /
WL-CSP



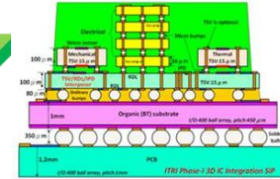
Fan-Out /
WLP/PLP



Package on
package



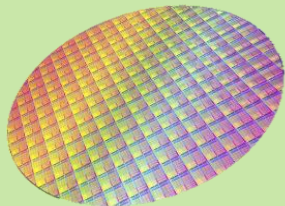
2.5D
- Fan-In/Out
- CoWoS



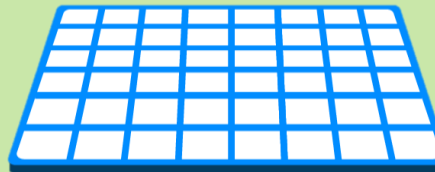
SoIC/
Hybrid Bond

*2D to 3D
Structure*

*Wide Range
Wafer Size*



75mm
100mm
125mm
150mm
200mm
300mm



300*300 mm
510*515 mm
600*600 mm

*Multi-
Application*

Advanced Package

- Flip Chip Bumping
- Fan Out Packaging
- 2.5D CoWoS
- 3D SoIC 、CPO

Compounded

- SiC
- GaAs/GaN
- InP

Automotive

- Diode
- CIS
- Micro LED

Others

- Bio Chip
- Crystal element
- IC Substrate

Product Development Focus on AI/HPC Advanced Package

■ GPTC

- Metal Etch
- PR Strip
- Cleaner

■ CLC

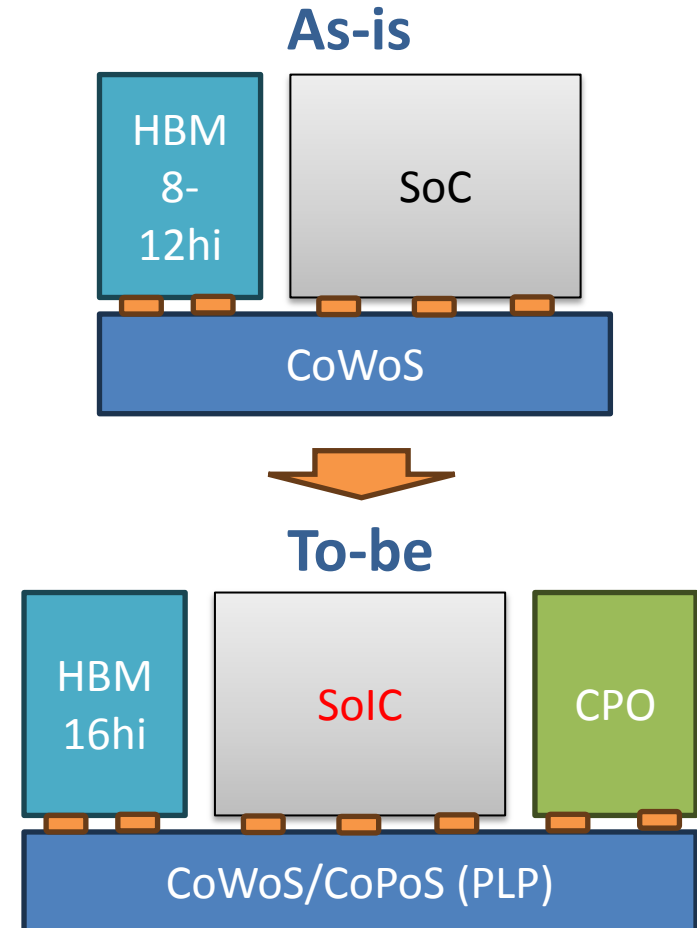
- Cu/Ti Etchant
- Environmentally PR Strip

■ CIC

- X-Ray Inspection
- CSAM Inspection
- End Point Detector for Wet Etch
- Concentration Monitor

■ TYNE

- Smart Monitor System for manufacturing Safety
- Engineering Data Analysis





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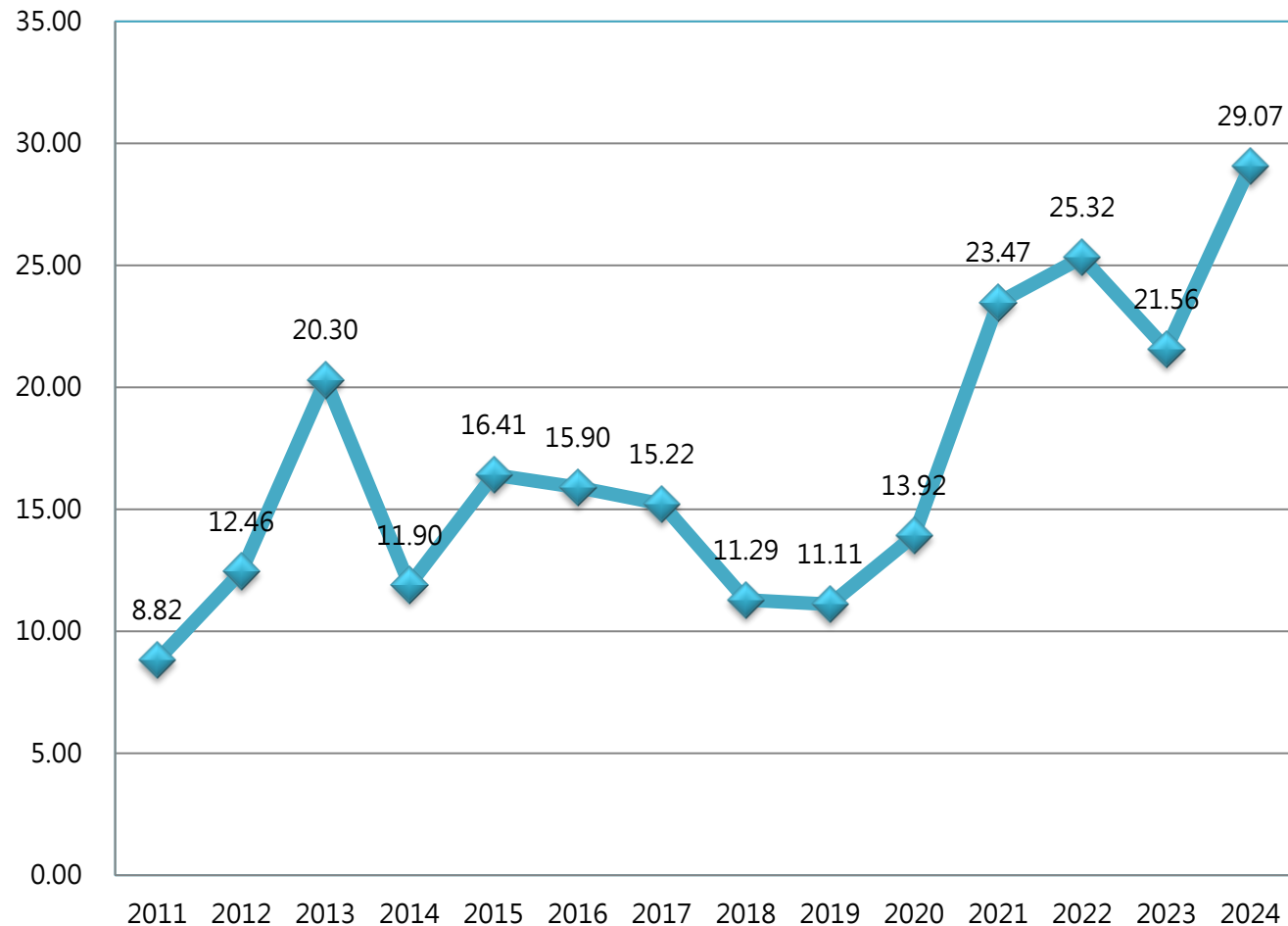
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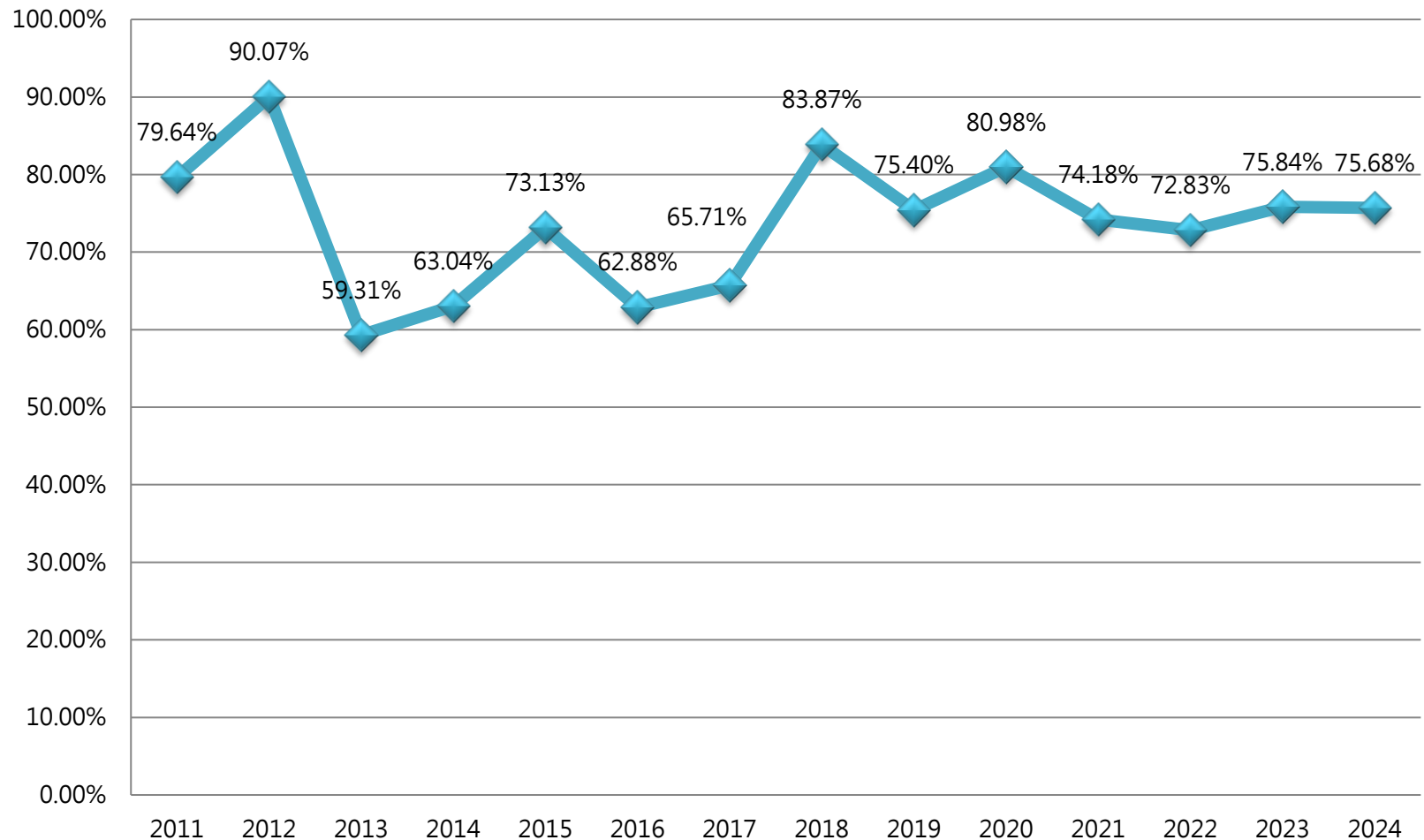
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歷年EPS趨勢



歷年股利配發率趨勢



THANKS

感 謝 聆 聽



弘塑集團